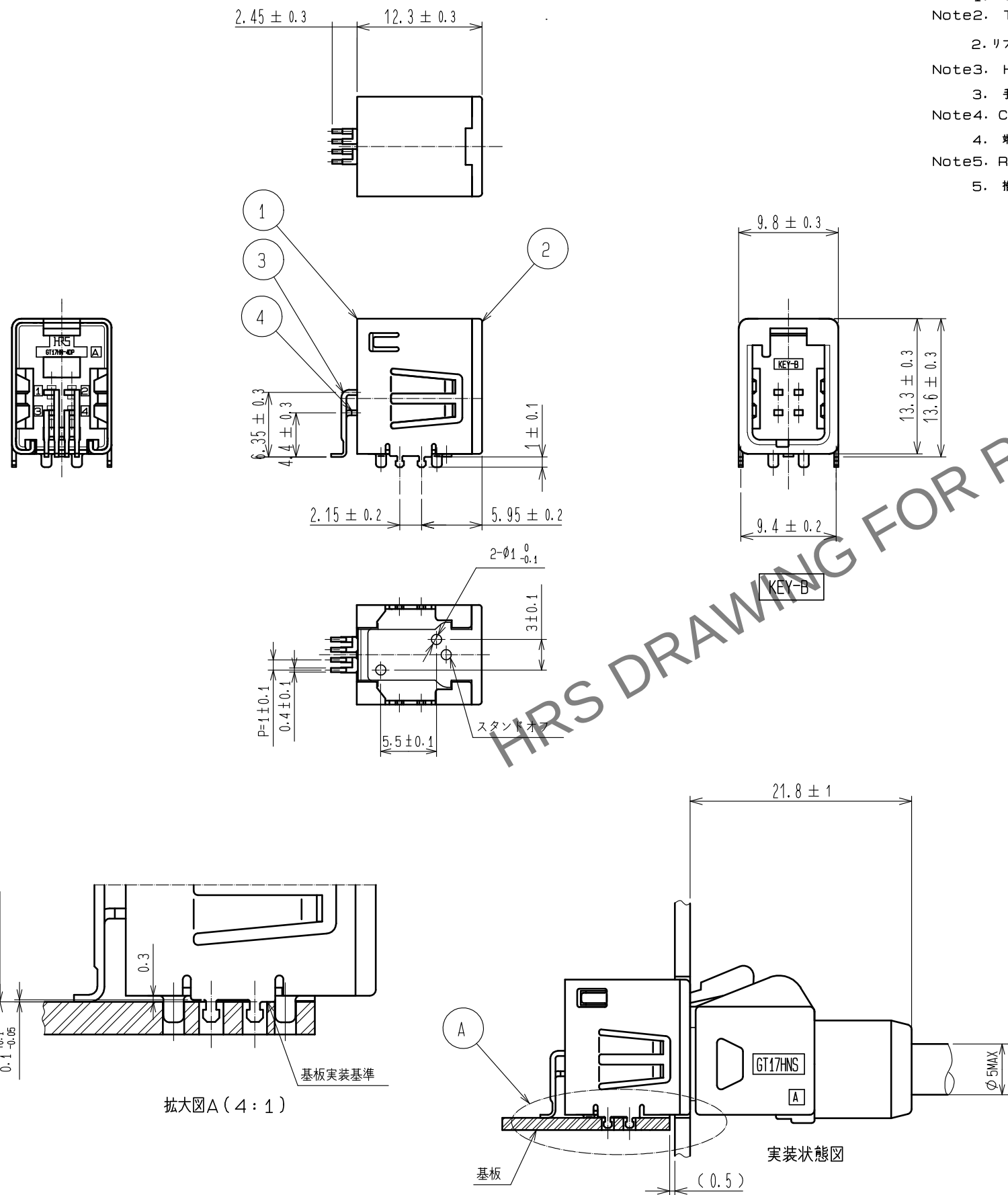


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In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

ELV, RoHS適合品

ELV, RoHS COMPLIANT



Note1. The soldering process is allowed up to twice under the same condition. However, the interval between the first and second process must be maintained at the room temperature.

1. リフロー回数: 2回, 但し, 2回目のリフローにおいては, 一度, 室温に戻すこと.

Note2. The temperature indicates the board surface temperature on the connector lead area.

2. リフロー温度の測定は, コネクタリード部の基板表面温度を測定のこと.

Note3. Hand soldering: 280~300℃, 2s max.

3. 手半田温度: 280~300℃, 2S以内

Note4. Coplanarity: 0.1 max.

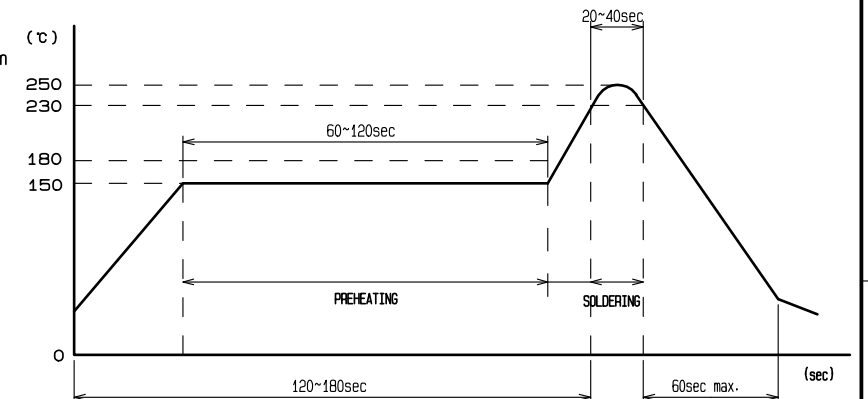
4. 端子平坦度: 0.1以下

Note5. Recommended thickness of PCB: 1.6mm

5. 推奨基板厚: 1.6mm

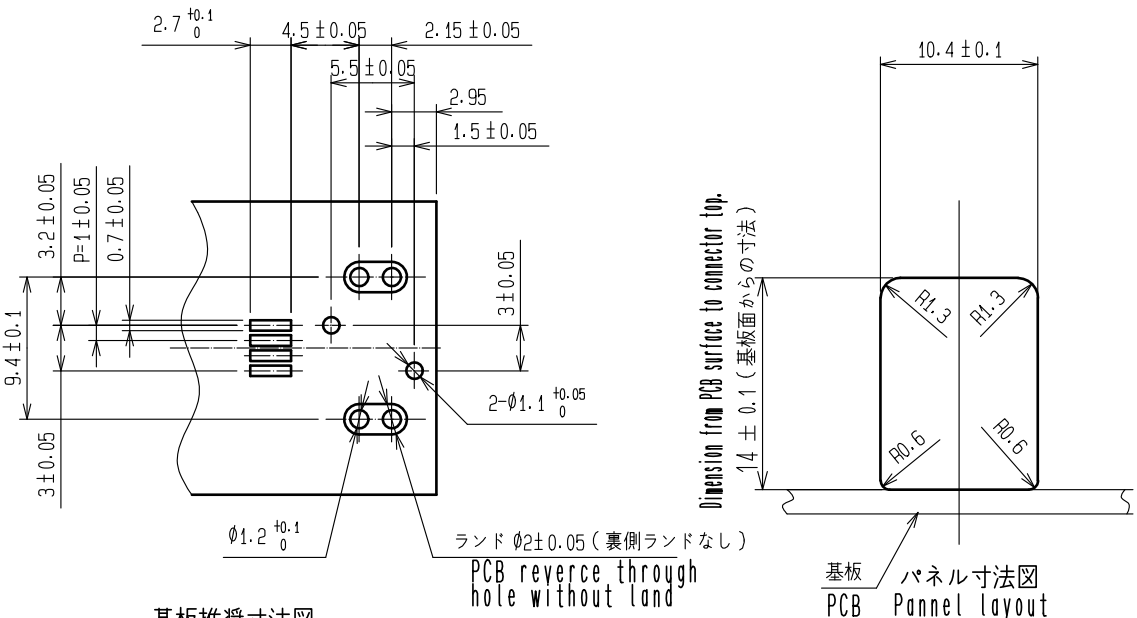
RECOMMENDED REFLOW PROFILE

IR reflow condition	IR リフロー条件
Preheating area 150℃ for 60 to 120 seconds	予熱加熱: 60~120秒, 150℃
Peak temperature: 250℃	ピーク温度: 250℃
Soldering area 235±5℃ or 10 seconds max.	リフロー温度: 230~240℃, 10秒以内
230℃ min. for 10 30 seconds	230℃以上: 10~30秒



8. コネクタと基板間のこじり荷重を回避するために, フランジなしの本製品は, 基板固定の機械的補強を設計的に配慮願います.

Note 6. For the prevention excessive stress for connector and PCB, we recommend additional support mechanism if the flange was eliminated.



基板推奨寸法図
Recommended PCB layout

3	BRASS	TIN PLATING	6	PS	
2	PPS	GREEN	5	PS	
1	COPPER ALLOY	TIN PLATING	4	BRASS	TIN PLATING
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 2 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED CHECKED DATE
APPROVED : KI. HIROKAWA		20200331	DRAWING NO. EDC-167010-65-00		
CHECKED : EJ. WAKATSUKI		20200330	PART NO. GT17HN-4DP-2H(B)(65)		
DESIGNED : TS. KUBOTA		20200325	CODE NO. CL767-0175-0-65		
DRAWN : YK. MITSUISHI		20200313			

